

RELIABILITY REPORT
FOR
MAX762ESA+
PLASTIC ENCAPSULATED DEVICES

October 29, 2010

MAXIM INTEGRATED PRODUCTS

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SUNNYVALE, CA 94086

Approved by
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Conclusion

The MAX762ESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX761/MAX762 step-up switching regulators provide high efficiency over a wide range of load currents, delivering up to 150mA. A unique, current-limited pulse-frequency-modulated (PFM) control scheme gives the devices the benefits of pulse-width-modulated (PWM) converters (high efficiency with heavy loads), while using less than 110 μ A of supply current (vs. 2mA to 10mA for PWM converters). The result is high efficiency over a wide range of loads. The MAX761/MAX762 input voltage range is 2V to 16.5V. Output voltages are preset to 12V (MAX761) and 15V (MAX762), or they can be set with two external resistors. With a 5V input, the MAX761 guarantees a 12V, 150mA output. Its high efficiency, low supply current, fast start-up time, SHDN controlling capability, and small size make the MAX761 ideal for powering flash memory. The MAX761/MAX762 have an internal 1A power MOSFET, making them ideal for minimum-component, low- and medium-power applications. These devices use tiny external components, and their high switching frequencies (up to 300kHz) allow for small surface-mount magnetics. For increased output drive capability or higher output voltages, use the MAX770-MAX773, which are similar in design to the MAX761/MAX762, but drive external power MOSFETs. For stepping up to 5V, see the MAX756/MAX757 and MAX856-MAX859 data sheets.

II. Manufacturing Information

A. Description/Function:	12V/15V or Adjustable, High-Efficiency, Low-I _Q , Step-Up DC-DC Converters
B. Process:	SG5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1701-0089
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	80 X 142 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 440 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 2.5 \times 10^{-9}$$

$\lambda = 2.5$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the SG5 Process results in a FIT Rate of 0.12 @ 25C and 2.04 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot NTBCEQOO2A, D/C 9931)

The PW08-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX762ESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NTBCFA017B, DC 0022
			80	0	NTBCEQ002A, DC 9931
			80	0	XTBCDX001A, DC 9649
			80	0	XTBCCY001A, DC 9403
			80	0	NTBBFA022A, DC 0034
			40	0	XTBBCQ001A, DC 9938

Note 1: Life Test Data may represent plastic DIP qualification lots.